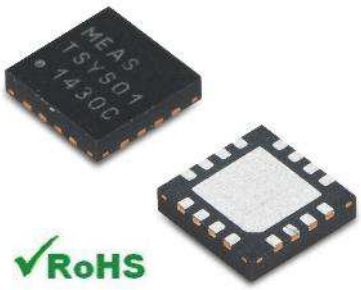


TSYS01-FAMILY

Digital Temperature Sensors

Specifications

- High Accuracy Temperature Sensor
- TSYS01: ±0.1°C @ Temp.: -5°C … +50°C
- TSYS01-1: ±0.1°C @ Temp.: -20°C … +70°C
- 16/24 bit Resolution
- Low Power
- SPI/I2C Interface
- QFN16 Package

Features

- High Accuracy
- TSYS01: ±0.1°C @ Temp.: -5°C … +50°C
  TSYS01-1: ±0.1°C @ Temp.: -20°C … +70°C
- Adjustment of high accuracy temp. range on request
- Low Current, <12.5 µA (standby < 0.14 µA)
- SPI / I2C Interface
- Small Package: QFN16
- Operating Temperature Range: -40°C … +125°C

The TSYS01 is a single device, versatile, new technology temperature sensor. The TSYS01 provides factory calibrated temperature information. It includes a temperature sensing chip and a 24-bit ΔΣ-ADC. The essence of the digital 24-bit temperature value and the internal calibration values lead to highly accurate temperature information accompanied by high measurement resolution.

The TSYS01 can be interfaced to any microcontroller by an I2C or SPI interface. This microcontroller has to calculate the temperature result based on the ADC values and the calibration parameters.

Applications

- Industrial Control
- Replacement of Thermistors and NTCs
- Heating / Cooling Systems
- HVAC

The basic operating principle is:

- Converting temperature into digital 16/24 bit ADC value
- Providing calibration coefficients
- Providing ADC value and calibration coefficients by SPI or I2C interface.

your distributor
www.amsys.de

Absolute maximum ratings

Absolute maximum ratings are limiting values of permitted operation and should never be exceeded under the worst possible conditions either initially or consequently. If exceeded by even the smallest amount, instantaneous catastrophic failure can occur. And even if the device continues to operate satisfactorily, its life may be considerably shortened.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage	V_{DD}	---	-0.3	---	+3.6	V
Operating Temperature	T_{op}	---	-40	---	+125	°C
Storage temperature	T_{stor}	---	-55	---	+150	°C
ESD rating	ESD	Human Body Model (HBM) pin to pin incl. V_{DD} & GND	-4	---	+4	kV
Humidity	Hum	---	Non condensing			---

Operating conditions

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Operating Supply Voltage	V_{DD}	Stabilized	2.2	---	3.6	V
High Accuracy Supply Voltage	V_{DD}	To achieve Acc1	3.2	---	3.4	V
Supply Current	I_{DD}	1 sample per second	---	---	12.5	µA
Standby current	I_S	No conversion, V_{DD} = 3V T = 25°C T = 85°C	---	 0.02 0.70	 0.14 1.40	 µA µA
Peak Supply Current	I_{DD}	During conversion	---	1.4	---	mA
Conversion time	T_{CONV}		7.40	8.22	9.04	ms
Serial Data Clock SPI	F_{SCLK}		---	---	20	MHz
Serial Data Clock I²C	F_{SCL}		---	---	400	kHz
V_{DD} Capacitor	---	Place close to the chip	---	100nF	---	---

Operational characteristics

If not otherwise noted, 3.3V supply voltage is applied.

Parameter	Symbol	Conditions		Min	Typ	Max	Unit
Temp. Measurement Range	T_{RANG}	---		-40	---	+125	°C
Accuracy 1	T_{ACC1}	TSYS01	-5°C < T < +50°C V_{DD} = 3.2V – 3.4V	-0.1	---	+0.1	°C
		TSYS01-1	-20°C < T < +70°C V_{DD} = 3.2V – 3.4V				
Accuracy 2	T_{ACC2}	-40°C < T < +125°C V_{DD} = 3.2V – 3.4V		-0.5	---	+0.5	°C
Power Supply Reject Ratio	PSRR	V_{DD} = 2.7 – 3.6 T = 25°C, C = 100nF		---	---	0.2	°C
Temperature Resolution	T_{RES}	---		---	---	0.01	°C
Time Constant	T_{liquid}	t_{63} (t_1 → t_2) t_1 = 25°C (air 0m/s) t_2 = 75°C (liquid) PCB 900mm² x 1.5mm FR4		---	3	---	s
	T_{air}	t_{63} (t_1 → t_2) t_1 = 25°C (air 0m/s) t_2 = 75°C (air stream 60m/s) PCB 900mm² x 1.5mm FR4		---	4	---	s
Self Heating	SH_1	10 samples/s, 60s, still air		---	---	0.02	°C

Analogue to digital converter

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output Word	---	---		24		bit
Conversion Time	t_c	---	7.40	8.22	9.04	ms

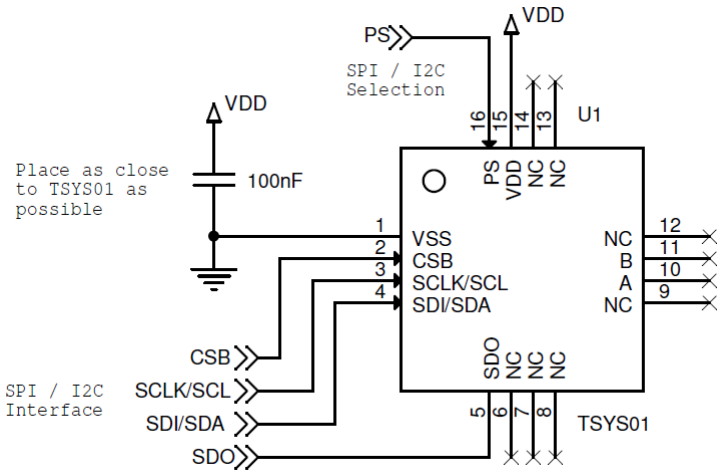
Digital inputs (SCLK, SDI, CSB, PS)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Input High Voltage	V_{IH}	V_{DD} = 2.2…3.6V	0.7•V_{DD}	---	V_{DD}	V
Input Low Voltage	V_{IL}	V_{DD} = 2.2…3.6V	0.0•V_{DD}	---	0.3•V_{DD}	V
CS low to first SCLK rising	t_{CSL}	---	21	---	---	ns
CS high to first SCLK rising	t_{CSH}	---	21	---	---	ns
SDI setup to first SCLK rising	T_{DSO}	---	6	---	---	ns
SDI hold to first SCLK rising	T_{DO}	---	6	---	---	ns

Digital outputs (SDA, SDO)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output High Voltage	V_{OH}	I_{Source} = 1mA	0.8•V_{DD}	---	V_{DD}	V
Output Low Voltage	V_{OL}	I_{Sink} = 1mA	0.0•V_{DD}	---	0.2•V_{DD}	V
SDO setup to first SCLK rising	t_{QS}	---	10	---	---	ns
SDO hold to first SCLK rising	t_{QH}	---	0	---	---	ns

Connection diagram



Pin function table

Pin	Name	Type	Function
1	V_{SS}	G	Ground
2	CSB	DI	SPI: Chip Select (active low) I^2C: Address Selection
3	SCLK/SCL	DI	SPI: Serial Data Clock I^2C: Serial Data Clock
4	SDI/SDA	DIO	SPI: Serial Data Input I^2C: Data Input / Output
5	SDO	DO	SPI: Serial Data Output
6 – 14	NC	---	Not connected / Do not connect
15	V_{DD}	P	Supply Voltage
16	PS	DI	Communication protocol select (0=SPI, 1=I^2C)
---	DAP	---	Die Attach Pad, suggested to connect to V_{SS}

Interface description

PROTOCOL SELECTION

PS pin input level has to be defined in dependence to protocol selection.

- PS = 0 activates SPI.
- PS = 1 activates I2C.

I^2C INTERFACE

A I^2C communication message starts with a start condition and it is ended by a stop condition.
Each command consists of two bytes: the address byte and command byte.

I^2C ADDRESS SELECTION

The I^2C address can be selected by CSB pin.

- CSB=1 the address is 1110110x.
- CSB=0 the address is 1110111x.

Therefore, two TSYS01 can be interfaced on the same I^2C bus.

SPI INTERFACE

The serial interface is a 4-wire SPI bus, operating as a slave. CS (chip select), SCLK (serial clock), SDI (serial data in), and SDO (serial data out) are used to interact with the SPI master.

Communication with the chip starts when CS is pulled to low and ends when CS is pulled to high.

SCLK is controlled by the SPI master and idles low (SCLK low on CS transitions, mode 0).

A mode where the clock alternatively idles high is also supported (mode 3).

COMMANDS

The commands are the same for SPI and I²C interface.

There are four commands:

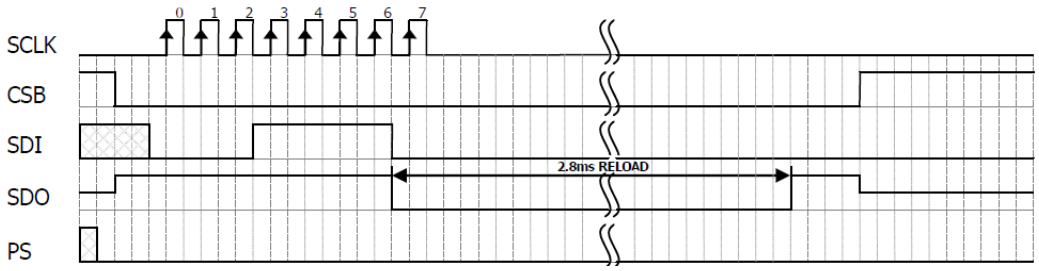
- Reset
- Read PROM (calibration parameters)
- Start ADC Temperature conversion
- Read ADC Temperature result

Command	Hex Value
Reset	0x1E
Start ADC Temperature Conversion	0x48
Read ADC Temperature Result	0x00
PROM Read Address 0	0xA0
PROM Read Address 1 (Coefficient k_4)	0xA2
PROM Read Address 2 (Coefficient k_3)	0xA4
PROM Read Address 3 (Coefficient k_2)	0xA6
PROM Read Address 4 (Coefficient k_1)	0xA8
PROM Read Address 5 (Coefficient k_0)	0xAA
PROM Read Address 6 ($SN_{23...8}$)	0xAC
PROM Read Address 7 ($SN_{7...0}$ and Checksum)	0xAE

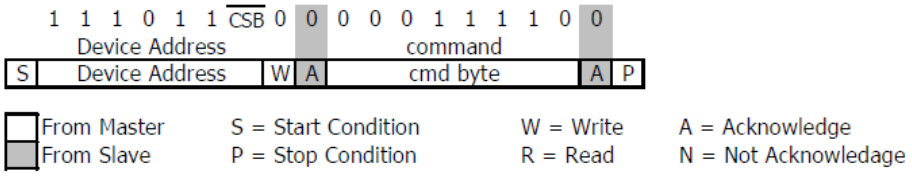
RESET SEQUENCE

The Reset sequence has to be sent once after power-on. It also can be used to reset the device ROM from an unknown condition.

SPI



I²C

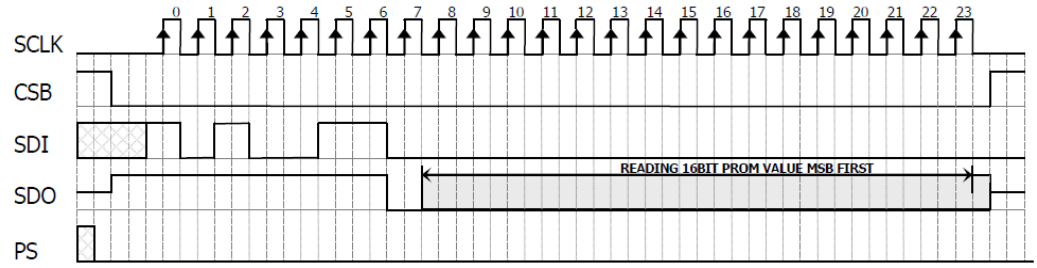


PROM READ SEQUENCE

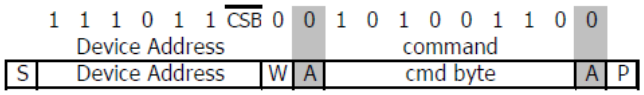
The PROM Read command consists of two parts. First command sets up the system into PROM read mode. The second part gets the data from the system.

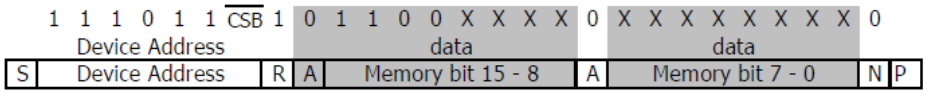
Below examples are sequences to read address 3 (command 0xA6).

SPI



I²C



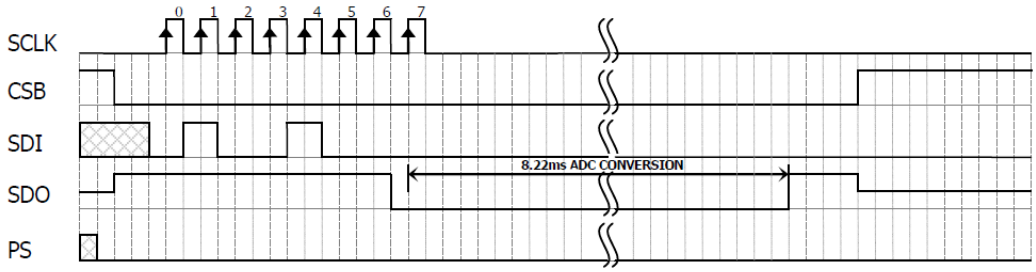


CONVERSION SEQUENCE

A conversion has to be started by sending this command. The sensor stays busy until conversion is done. When conversion is finished the data can be accessed by using ADC read command

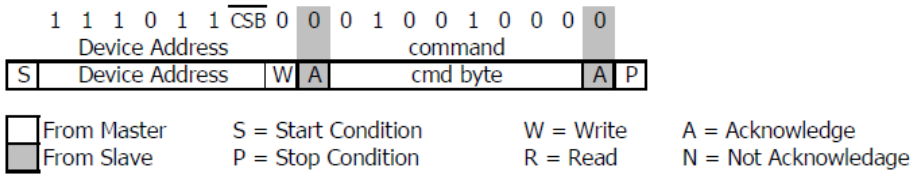
SPI

The last clock will start the conversion which TSYS01 indicates by pulling SDO low. SDO goes high when conversion is completed.



I²C

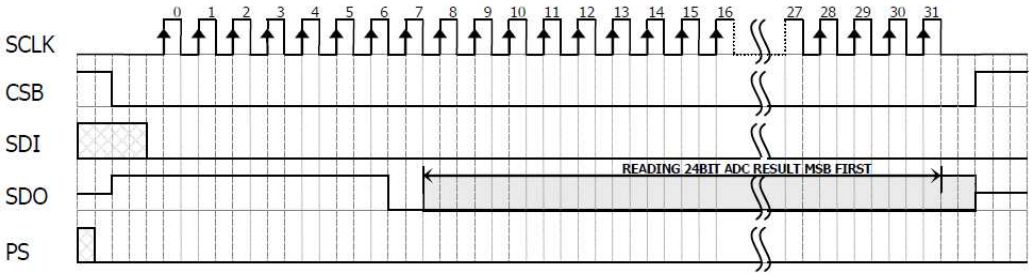
When the command is sent the TSYS01 stays busy until the conversion is done. All other commands except the reset command will not be executed during this time. When the conversion is finished the data can be accessed by sending a ADC read command, when an acknowledge appears from TSYS01.



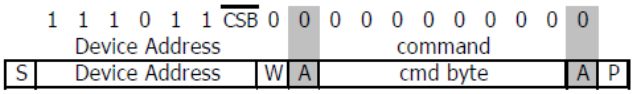
READ ADC RESULT

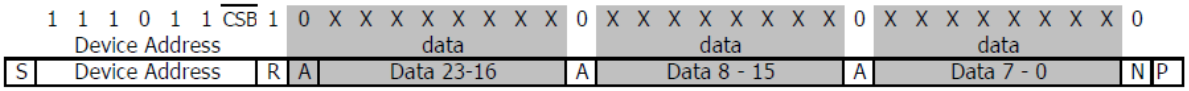
After the conversion command the ADC result is read using ADC read command. Repeated ADC read commands, or command executed without prior conversion will return all 0 as result.

SPI

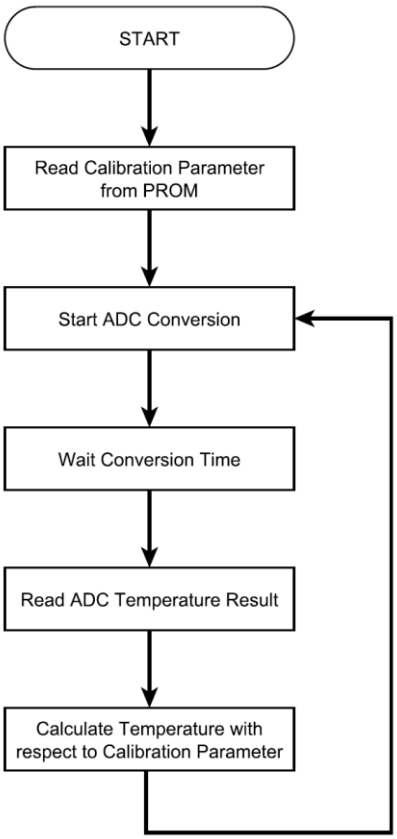


I²C





Temperature calculation



CALIBRATION PARAMETER

Variable	Description	Command	Size / bit	Min	Max	Example
k_4	Coefficient k_4 of polynomial	0xA2	16	0	65535	28446
k_3	Coefficient k_3 of polynomial	0xA4	16	0	65535	24926
k_2	Coefficient k_2 of polynomial	0xA6	16	0	65535	36016
k_1	Coefficient k_1 of polynomial	0xA8	16	0	65535	32791
k_0	Coefficient k_0 of polynomial	0xAA	16	0	65535	40781

TEMPERATURE POLYNOMAL

ADC24: ADC value
ADC16: ADC24 / 256

$$T / °C = (-2) * k_4 * 10^{-21} * ADC16^4 + 4 * k_3 * 10^{-16} * ADC16^3 + (-2) * k_2 * 10^{-11} * ADC16^2 + 1 * k_1 * 10^{-6} * ADC16 + (-1.5) * k_0 * 10^{-2}$$

EXAMPLE

ADC24: 9378708
ADC16: 9378708 / 256 = 36636

$$
\begin{aligned}
T / °C = \quad & (-2) \quad * 28446 * 10^{-21} * 36636^4 + \\
& 4 \quad * 24926 * 10^{-16} * 36636^3 + \\
& (-2) \quad * 36016 * 10^{-11} * 36636^2 + \\
& 1 \quad * 32791 * 10^{-6} \quad * 36636 \quad + \\
& (-1.5) \; * 40781 * 10^{-2}
\end{aligned}
$$

T / °C = 10.59

Serial number

Content / Description		Command	Size / bit	Example
Bit 16 … 8	Bit 7 … 0			
$SN_{23...8}$		0xAC	16	0x0005 (H_0 = 0x00, L_0 = 0x05)
$SN_{7...0}$	Checksum	0xAE	16	0x96D9 (H_0 = 0x96, L_0 = 0xD9)

Serial number = 2^8 x $SN_{23...8}$ + $SN_{7...0}$

EXAMPLE

Serial number: 2^8 x 5 + 150 = 1430

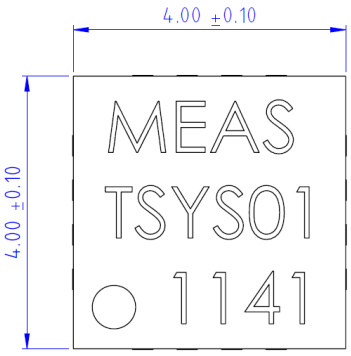
Checksum

In order to check communication and integrity of PROM content, the PROM includes a checksum. By summarization of the complete PROM content in a byte by byte way, the verification can be performed. The lower byte of the sum result has to be 0x00.

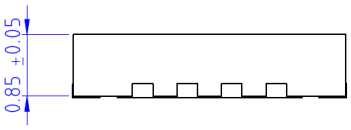
Dimensions

TOP VIEW

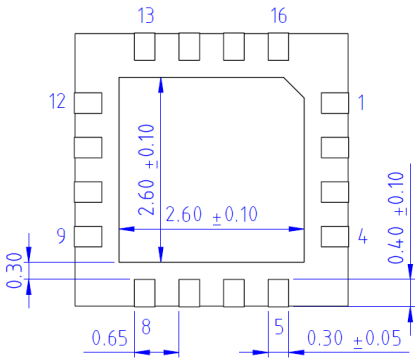
All dimensions shown in mm



SIDE VIEW



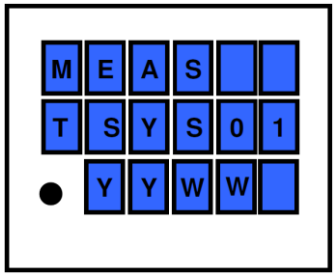
BOTTOM VIEW



Die Attach Pad, suggested to connect to VSS

Marking

Line	Description	Example
1	Manufacturer	MEAS
2	Product Name	TSYS01
3	Pin 1 Dot, Date Code YYWW	1141



Order information

Please order this product using following:

Part Number	Part Description
G-NICO-018	TSYS01 Digital Temperature Sensor
G-NICO-023	TSYS01-1 Digital Temperature Sensor

EMC

Due to the use of these modules for OEM application no CE declaration is done. Especially line coupled disturbances like surge, burst, HF etc. cannot be removed by the module due to the small board area and low price feature. There is no protection circuit against reverse polarity or over voltage implemented. The module

will be designed using capacitors for blocking and ground plane areas in order to prevent wireless coupled disturbances as good as possible.

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